

| Type number | Package | Package description | Total product weight |
|-------------|---------|---------------------|----------------------|
| PMN15ENE | SOT457 | SC-74 | 12.57330 mg |

| 12NC | Version | Pb-free soldering | | | Pb soldering | | | Number of processing cycles | Assembly site | RHF-indicator |
|--------------|---------|-------------------|-----|------|--------------|-----|------|-----------------------------|---|---------------|
| | | MSL | PPT | MPPT | MSL | PPT | MPPT | | | |
| 934664406115 | 1 | 1 | 260 | 30 s | 1 | 235 | 20 s | 3 | Dongguan, China; D-22529 HAMBURG, Germany; Manchester, United Kingdom | |

| Subpart | Material group | Substances | CAS number | Mass(mg) | Mass(%) of subpart | Mass(%) of total product |
|----------------|------------------|---|--------------|-------------|--------------------|--------------------------|
| Adhesive | Filler | Silver (Ag) | 7440-22-4 | 0.05236 | 77.00000 | 0.41644 |
| | | Polymer | Resin system | Proprietary | 0.01564 | 23.00000 |
| | | | subTotal | | 0.06800 | 100.00000 |
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.47000 | 100.00000 | 3.73808 |
| | | | subTotal | 0.47000 | 100.00000 | 3.73808 |
| Lead Frame | Copper alloy | Copper (Cu) | 7440-50-8 | 4.50440 | 95.17000 | 35.82509 |
| | | Iron (Fe) | 7439-89-6 | 0.10744 | 2.27000 | 0.85450 |
| | | Phosphorous (P) | 7723-14-0 | 0.00331 | 0.07000 | 0.02635 |
| | | Zinc (Zn) | 7440-66-6 | 0.00568 | 0.12000 | 0.04517 |
| | Pure metal layer | Silver (Ag) | 7440-22-4 | 0.11217 | 2.37000 | 0.89215 |
| | | | subTotal | 4.73300 | 100.00000 | 37.64326 |
| Mould Compound | Filler | Silica -amorphous- | 7631-86-9 | 2.36617 | 35.07000 | 18.81903 |
| | | Silica fused | 60676-86-0 | 2.95788 | 43.84000 | 23.52513 |
| | Pigment | Carbon black | 1333-86-4 | 0.01687 | 0.25000 | 0.13415 |
| | Polymer | Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic) | 29690-82-2 | 0.67470 | 10.00000 | 5.36613 |
| | | Phenol Formaldehyde resin (generic) | 9003-35-4 | 0.67065 | 9.94000 | 5.33394 |
| | | Polyethylene (PE) -wax- | 9002-88-4 | 0.06072 | 0.90000 | 0.48295 |
| | | subTotal | 6.74700 | 100.00000 | 53.66133 | |
| Post-Plating | Impurity | Antimony (Sb) | 7440-36-0 | 0.00005 | 0.01000 | 0.00039 |
| | | Bismuth (Bi) | 7440-69-9 | 0.00010 | 0.02000 | 0.00077 |
| | | Iron (Fe) | 7439-89-6 | 0.00005 | 0.01000 | 0.00039 |
| | | Lead (Pb) | 7439-92-1 | 0.00005 | 0.01000 | 0.00039 |
| | Tin solder | Tin (Sn) | 7440-31-5 | 0.48576 | 99.95000 | 3.86340 |
| | | subTotal | 0.48600 | 100.00000 | 3.86534 | |
| Wire | Impurity | Non hazardous | Proprietary | 0.00001 | 0.01000 | 0.00006 |
| | Pure metal | Copper (Cu) | 7440-50-8 | 0.06929 | 99.99000 | 0.55111 |
| | | subTotal | 0.06930 | 100.00000 | 0.55117 | |

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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